

Reaction Bonded Silicon Carbide ceramic
 Technical Parameter of SISIC products

Item	Unit	Data
temperature of application	°C	1380
density	g/cm ³	>3.02
open porosity	%	<0.1
bending strength	Mpa	250(20°C)
	Mpa	280(1200°C)
modulus of elasticity	Gpa	330(20°C)
	Gpa	300(1200°C)
thermal conductivity	W/m.k	45(1200°C)
coefficient of thermal expansion	k ⁻¹ × 10 ⁻⁶	4.5
Vickers Hardness HV ₁₀	Gpa	20
acid-proof alkaline		Excellent

The values for above are the typical result from the test,not the promised exactly data applied to all orders

CERATEK TECHNICAL CERAMIC CO., LIMITED
 Tel/Fax:+86 21 33876960 Mobile:+86 13818729891
 Email:info@ceratek.net Web:www.ceratek.net